

## ABSTRACT OF THE DISCLOSURE

A thin-film semiconductor device with a reduced influence on a device formation layer in separation and a method of manufacturing the device are provided. The  
5 manufacturing method includes the step of preparing a member having a semiconductor film with a semiconductor element and/or semiconductor integrated circuit on a separation layer, the separation step of separating the member at the separation layer by a pressure of a fluid,  
10 and the chip forming step of, after the separation step, forming the semiconductor film into chips.